

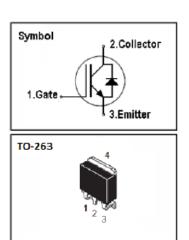
IGBT

Features

- 650V,20A
- $V_{CE(sat)(typ.)}$ =2.0V@ V_{GE} =15V, I_{C} =20A
- High speed switching
- Higher system efficiency
- Soft current turn-off waveforms
- Square RBSOA

General Description

JIAEN Trench IGBTs offer lower losses and higher energy efficiency for application such as Motor control, general inverter and other soft switching applications.



Absolute Maximum Ratings

Symbol	Parameter	Value	Units
Vces	Collector-Emitter Voltage	650	V
V _{GES}	Gate-Emitter Voltage	<u>+</u> 30	V
	ontinuous Collector Current (Tc=25 °C) 40		Α
lc	Continuous Collector Current (Tc=100°C)	20	Α
Ісм	Pulsed Collector Current (Note 1)	60	Α
I _F	Diode Continuous Forward Current (T _C =100 °C)	20	Α
I _{FM}	Diode Maximum Forward Current (Note 1)	60	Α
t _{sc}	Short Circuit Withstand Time	10	us
Б	Maximum Power Dissipation (T _C =25 ℃)	139	W
P _D	Maximum Power Dissipation (T _C =100 °C)	56	W
TJ	Operating Junction Temperature Range	-55 to +150	$^{\circ}$ C
Tstg	Storage Temperature Range	-55 to +150	$^{\circ}$ C

Thermal Characteristics

Symbol	Symbol Parameter		Units
R _{th j-c}	Thermal Resistance, Junction to case for IGBT	0.9	°C/W
R _{th j-c}	Thermal Resistance, Junction to case for Diode	1.6	°C/W
R _{th j-a}	Thermal Resistance, Junction to Ambient	62.5	°C/W



Electrical Characteristics (Tc=25 °C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
BV _{CES}	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V, I_{C} = 250uA$	650	-	-	V
I _{CES}	Collector-Emitter Leakage Current	$V_{CE} = 650 \text{V}, V_{GE} = 0 \text{V}$	-	-	100	uA
I _{GES}	Gate Leakage Current, Forward	V_{GE} = $\pm 20V$, V_{CE} = $0V$	-	-	±100	nA
V _{GE(th)}	Gate Threshold Voltage	$V_{GE} = V_{CE}$, $I_C = 250uA$	5.1	-	6.9	V
V _{CE(sat)}	Collector-Emitter Saturation Voltage	V _{GE} =15V, I _C = 20A	-	2.0	2.5	V
Qg	Total Gate Charge	Vcc=480V	-	271		nC
Qge	Gate-Emitter Charge	V _{GE} =15V	-	70		nC
Qgc	Gate-Collector Charge	Ic=20A	-	131		nC
t _{d(on)}	Turn-on Delay Time		-	17	-	ns
t r	Turn-on Rise Time	V _{cc} =400V	-	31	-	ns
t d(off)	Turn-off Delay Time	V _{GE} =15V	-	71	-	ns
t f	Turn-off Fall Time	1l _C =20A R _G =15Ω	-	99	-	ns
Eon	Turn-on Switching Loss	Inductive Load	-	0.46	-	mJ
Eoff	Turn-off Switching Loss	T _C =25 ℃	-	0.41	-	mJ
Ets	Total Switching Loss		-	0.87	-	mJ
C _{ies}	Input Capacitance	V _{CE} =25V	-	831	-	pF
Coes	Output Capacitance	V _{GE} =0V	-	50	-	pF
C _{res}	Reverse Transfer Capacitance	f = 1MHz	-	7.5	-	pF

$\underline{\textbf{Electrical Characteristics of Diode}}_{(T_C=25\,{}^{\circ}\!\text{C unless otherwise noted })}$

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V _F	Diode Forward Voltage	I _F =20A	-	1.5	3.0	V
trr	Diode Reverse Recovery Time	V _{CE} = 400V	-	110		ns
Irr	Diode peak Reverse Recovery Current	I _F = 20A	-	16.6		Α
Qrr	Diode Reverse Recovery Charge	Rg=15 Ω	-	736		nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature



Typical Performance Characteristics

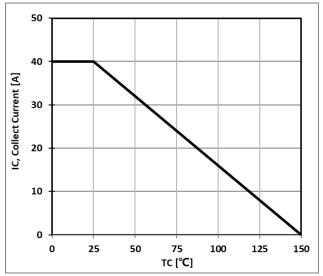


Figure 1: Maximum DC Collector Current VS. case temprature

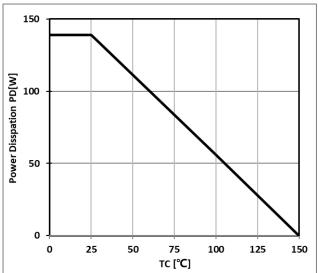


Figure 2: Power Dissipation VS. Case Temperature

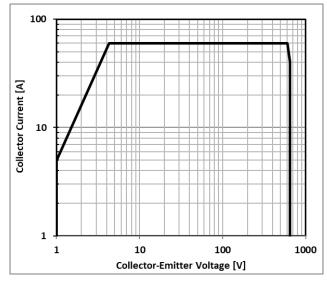


Figure 3: Reverse Bias SOA,TJ=125℃,VGE=15V

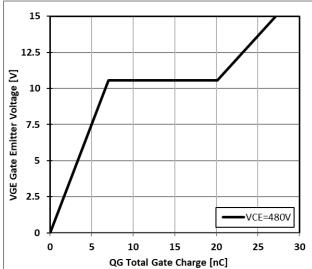


Figure 4: Typical Gate charge VS. VGE,IC=20A



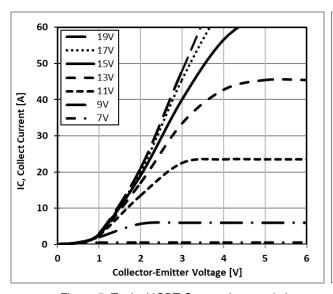


Figure 5: Typical IGBT Output characteristics, $TC=25^{\circ}C$;tp=300us

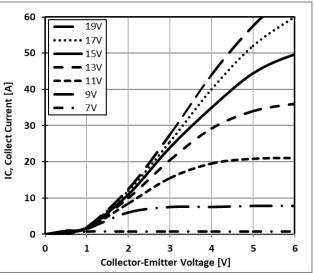


Figure 6: Typical IGBT Output characteristics, TC=150°C;tp=300us

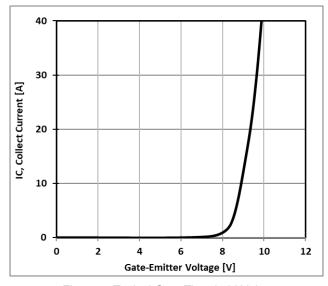


Figure 7: Typical Gate Threshold Voltage

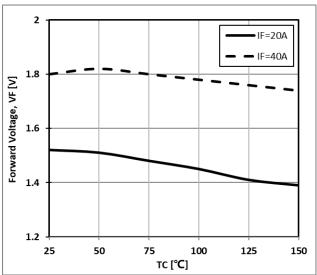


Figure 8: Typical Forward Voltage vs IF



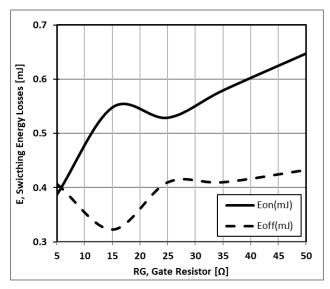


Figure 9: Typical Energy Loss VS. RG, TC=25 °C, L=200uH,VCE=400V,VGE=15V,IC=20A

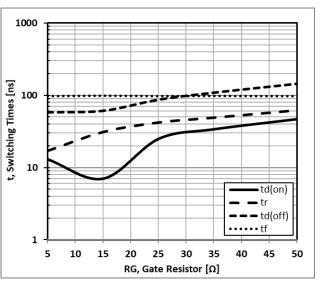


Figure 10: Typical Switching Time VS. RG, TC=25°C, L=200uH,VCE=400V,VGE=15V,IC=20A

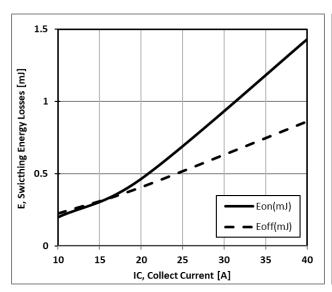


Figure 11: Typical Energy Loss VS. IC,TC=25 $^{\circ}$ C, L=200uH, VCE=400V, VGE=15V,RG=15 $^{\Omega}$

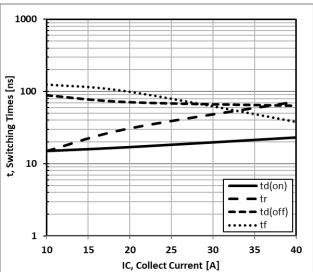


Figure 12: Typical Switching Time VS. IC,TC=25 $^{\circ}$ C, L=200uH,VCE=400V,VGE=15V,RG=15 $^{\circ}$



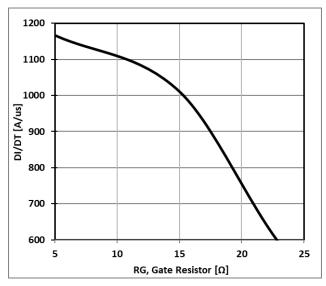


Figure 13: Typical Diode DI/DT VS. RG,TC=25°C VCC=400V, VGE=15V, IF=20A

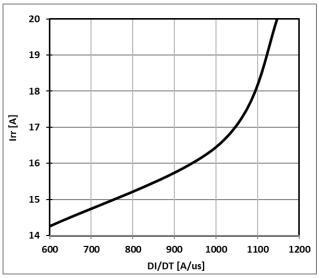


Figure 14: Typical Diode IRR VS. DI/DT,TC=25°C VCC=400V,VGE=15V, IF=20A

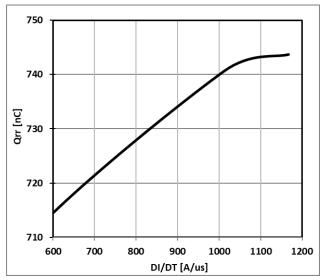


Figure 15: Typical Diode Qrr VS. DI/DT,TC=25℃ VCC=400V, VGE=15V, IF=20A

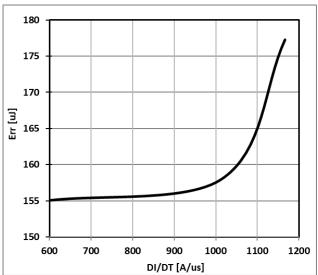


Figure 16: Typical Diode Err VS. DI/DT,TC=25 $^{\circ}$ C VCC=400V, VGE=15V, IF=20A



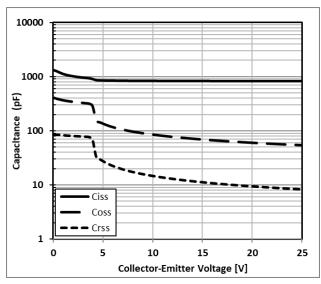


Figure 17: Typical Capacitance VS. VCE, VGE=0V,f=1MHz

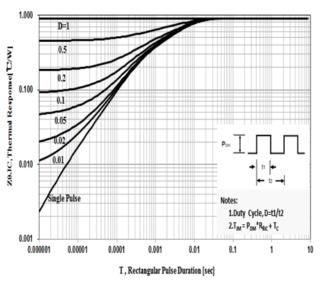
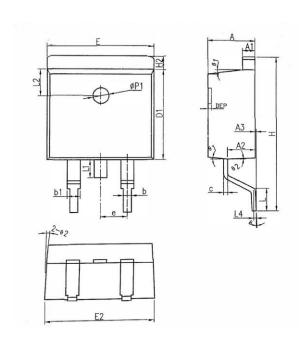


Figure 18: Normalized transient thermal impedance junction-to-case





TO-263 PACKAGE OUTLINE



SYMBOL	MM		NCH.					
	MIN	NOM	MAX	MIN	NOM	MAX		
Α	4.40	4.57	4.70	0.173	0.180	0.185		
A1	1.22	1.27	1.32	0.048	0.050	0.052		
A2	2.59	2.69	2.79	0.102	0.106	0.110		
A3	0.00	0.10	0.20	0.000	0.004	0.008		
b	0.77	0.813	0.90	0.030	0.032	0.035		
b1	1.20	1.270	1.36	0.047	0.050	0.054		
С	0.34	0.381	0.47	0.013	0.015	0.019		
D1	8.60	8.70	8.80	0.339	0.343	0.346		
E	10.00	10.16	10.26	0.394	0.400	0.404		
E2	10.00	10.10	10.20	0.394	0.398	0.402		
е	2.54 BSC			0.100 BSC				
Н	14.70	15.10	15.50	0.579	0.594	0.610		
H2	1.17	1.27	1.40	0.046	0.050	0.055		
L	2.00	2.30	2.60	0.079	0.091	0.102		
L1	1.45	1.55	1.70	0.057	0.061	0.067		
L2	2.50 REF				0.098 REF			
L4	0.25 BSC			0.010 BSC				
θ	0°	5°	8°	0°	5°	8°		
θ1	5°	7°	9°	5°	7°	9°		
θ2	1°	3°	5°	1°	3°	5°		
ФР1	1.40	1.50	1.60	0.055	0.059	0.063		
DEP	0.05	0.10	0.20	0.002	0.004	0.008		



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